# Die Shear Strength

MIL-STD 883 Method 2019

PURPOSE. The purpose of this test is to determine the integrity of materials and procedures used to attach semiconductor die or surface mounted passive elements to package headers or other substrates. This determination is based on a measure of force applied to the die, the type of failure resulting from this application of force (if failure occurs) and the visual appearance of the residual die attach media and substrate/header metallization.

**Test Results**

| Part | Description | Condition | Sample Size | Date | Results |
|---|---|---|---|---|---|
| MM1H-0320LCH-2 | MMIC Mixer 3 - 20 GHz | - | 3 | 8/29/18 | Pass |
| MM2K-0530LCH-2 | MMIC Mixer 5 - 30 GHz | - | 2 | 4/11/18 | Pass |
| MM1K-1140HCH-2 | MMIC Mixer RF 11 - 40 GHz | - | 2 | 2/9/18 | Pass |
| MM1H-0320LCH-2 | MMIC Mixer 3 - 20 GHz | - | 2 | 1/30/18 | Pass |
| MM1H-1140HCH-2 | MMIC Mixer RF 11 - 40 GHz | - | 2 | 1/18/18 | Pass |
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